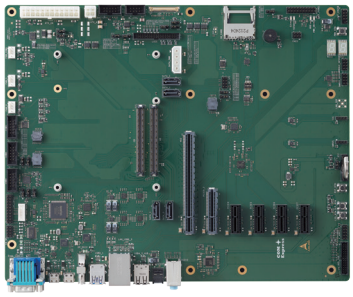
ADLINK
LEADING EDGE COMPUTING

Express-BASE6 R3.1

COM Express® R3.1 Comply Type 6 Reference Carrier Board in ATX Form Factor



Specifications

Core Module Interface	PICMG COM Express Revision 3.1 Support R3.1 Type 6 modules Basic / Compact size
Dimension	305 mm x 244 mm (ATX)
Expansion Busses	1x PCI Express x16 slot 1x PCI Express x4 slot (PCIe lane 0-3) 4x PCI Express x1 slot (PCIe lane 4, 5, 6, 7)
POST LEDs	Onboard diagnostics for BIOS POST code data on LPC bus
Secondary BIOS	Onboard socket for secondary SPI flash
COM Express Connectors	Two x 220-pin (8mm height)
HDMI	HDMI vertical connector on Rear I/O (DDI 3)
USB4	2x USB4 at Type C on Rear I/O*
VGA	DB15 on Rear I/O*
Flat Panel	34-pin header LVDS (build option for eDP*)
Audio	Mic/Line-in/Line-out on Rear I/O S/PDIF on Rear I/O
SATA	4x SATA (with power for SATA device)
USB	4x USB 3.x/2.0/1.1 Type A on Rear I/O 2x USB 2.0/1.1 Type A on Rear I/O 2x USB 2.0/1.1 at 9-pin header for front panel
LAN	2500/1000/100/10BASE-T compatible RJ45 on Rear I/O
GPIO/SD	8-pin header GPIO, SD card slot*
Serial Port	1x DB-9 (from Super I/O) on Rear I/O 3x 10-pin header
FAN	1x 4-pin FAN connector (from COMe module) 2x 4-pin FAN connector (from Super I/O)
Feature Connectors	Headers for SMBus, I^2C, LPC Header for front panel usage Others for module control signals
Miscellaneous	BTN (ON/OFF, Reset, SLEEP, LID), LED, Buzzer

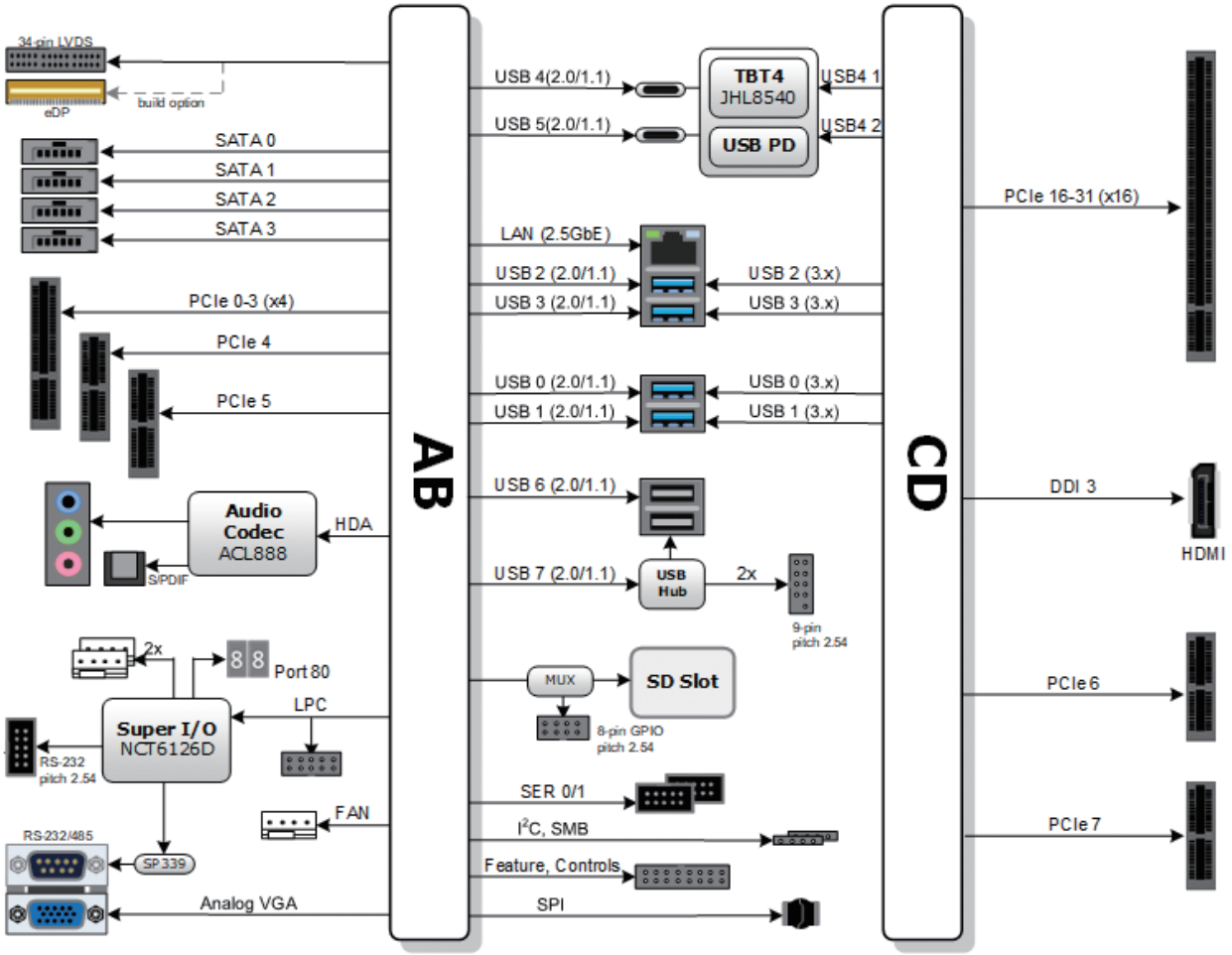
* Interface and signal compatibility is subject to the module and carrier used.

LRI Distribuída no Brasil pela LRI | vendas@lri.com.br | 51 2129-3000

Ordering Information

Carrier	
Express-BASE6 R3.1	COM Express® Type 6 R3.1 Reference Carrier Board in ATX Form Factor

Block diagram



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